

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-6 (Canceled)

7.(Currently Amended) An electronic device comprising a substrate with an electrical element on its first side which element comprises a first and a second electrode which are connected to a metallization by electrical contacts and electrodes of further electrical elements, the electronic device further comprising an inductive element, characterized in that the inductive element is defined in an electroconductive patterned layer which is located on the first side of the substrate and which is electroconductively connected to the metallization, isolating material being present between said substrate and the patterned layer in which isolating material the patterned layer has been

mechanically embedded, wherein the isolating material is in contact with the substrate and the patterned layer and surrounds the substrate and the patterned layer.

8. (Currently Amended) ~~An~~ The electronic device as claimed in claim 7, ~~characterized in that wherein~~ the patterned layer extends in a plane parallel to the first side beyond the substrate and contact pads for external contacting of the electronic device and the isolating material ~~in essence~~ substantially completely envelops the substrate.

9. (Currently Amended) ~~An~~ The electronic device as claimed in claim 7, ~~characterized in that wherein~~ the patterned layer is situated between the isolating material and additional layers in which vertical interconnect areas (vias) are defined.

10. (Currently Amended) ~~An~~ The electronic device as claimed in claim 7, ~~characterized in that wherein~~ the metallization along a boundary face with the isolating material includes ~~an~~ further inductive element which is situated substantially opposite the

inductive element in the patterned layer, the inductive ~~elements~~
element and the further inductive element together forming a strip
line.

11. (Currently Amended) ~~An~~ The electronic device as claimed in
claim 7, ~~characterized in that wherein~~ the substrate comprises a
semiconductor material selected from the group of III-V and II-VI
connectors and in that the electrical element is a semiconductor
element.

12. (New) The electronic device of claim 7, wherein a distance
between the substrate and the inductive element is larger than a
distance between the substrate and the electrical contacts.

13. (New) The electronic device of claim 7, wherein the
patterned layer is bent to place the inductive element in a plane
substantially parallel to the first side and at a desired distance
from the substrate, wherein the desired distance is larger than a
distance between the substrate and the electrical contacts.

14.(New) The electronic device of claim 7, wherein the patterned layer is bent to place the inductive element at a desired distance from the substrate, wherein the desired distance is larger than a distance between the substrate and the electrical contacts.

15.(New) The electronic device of claim 7, wherein the electrical contacts have a larger width than a width of the inductive element.